



Material Content Data Sheet



Sales Product Name	TLE4209G			Issued	20. July 2018			
MA#	MA001290868							
Package	PG-DSO-14-22			Weight*	142.95 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.173	2.22	2.22	22199	22199
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		106	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8443	
wire	non noble metal	copper	7440-50-8	49.007	34.28	35.17	342837	351808
	noble metal	gold	7440-57-5	0.217	0.15	0.15	1520	1520
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1206
encapsulation	plastics	epoxy resin	-	7.928	5.55		55462	
	inorganic material	silicondioxide	60676-86-0	78.074	54.62	60.29	546179	602847
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8578	8578
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7204	7204
glue	plastics	acrylic resin	-	0.184	0.13		1286	
	noble metal	silver	7440-22-4	0.652	0.46	0.59	4558	5844
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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